

IKA professional distribution board, IP65 + clamps

Powering Business Worldwide[™]

Part no. IKA-1/6-ST Catalog No. 174222 Eaton Catalog No. IKA-1/6-ST

110	INCE	nro	gram
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- control programs			
Basic function			Basic device
Product function			Installation distribution boards
Product range			IKA professional DBO
Design			Surface mounted
Installation site			Indoor
Type of installation			Surface mounting
Door/Flap			Transparent
Degree of Protection			IP65
Colour			Grey
Module rack			Single-rail
Shroud for protection against accidental contact			Plastic
Rows	Count		1
Module units per row			6
Description			IP65 Protection Class II Plastic enclosure gray (RAL 7035)
Cable entries			Metric cable entries on top and bottom, back plate
PE and N terminals design			Screw terminals
PE and N terminals	Number x cross- sectional area	mm ²	PE: 2 x (2.5 - 6) + 2 x (4 - 10) + 1 x (16 - 35) N: 2 x (2.5 - 6) + 2 x (4 - 10) + 1 x (16 - 35)
Equipment supplied			Basic device Device support rails Neutral-/protective conductor terminal Locking screws can be sealed Sealing caps Current circuit designation Reserve section cover 6 space units

Technical data

General

Standards			EN 62208, IEC/EN 60670-24
RoHS (in accordance with Directive 2002/95/EC of the European Parliament and Council)			conform
Ambient temperature		°C	-25 - +40
Degree of Protection			IP65
Protection class			II (totally insulated)
Rated operational voltage	Ue	V AC	415
Rated frequency	f	Hz	50
Material characteristics			

Material

Material	ABS (plastic)
Colour	Gray (RAL 7035)
Material properties	

Impact resistance IK08	Mechanical	
	Impact resistance	IK08

Design verification as per IEC/EN 61439

Technical data for design verification			
Heat dissipation, at an ambient temperature of 35°C, delta T: 20 degrees, calculated as per IEC 60890			
Individual enclosure for wall mounting	P_{V}	CO	13
Heat dissipation, at an ambient temperature of 35°C, delta T: 35 degrees, calculated as per IEC 60890			
Individual enclosure for wall mounting	P_{V}	CO	25

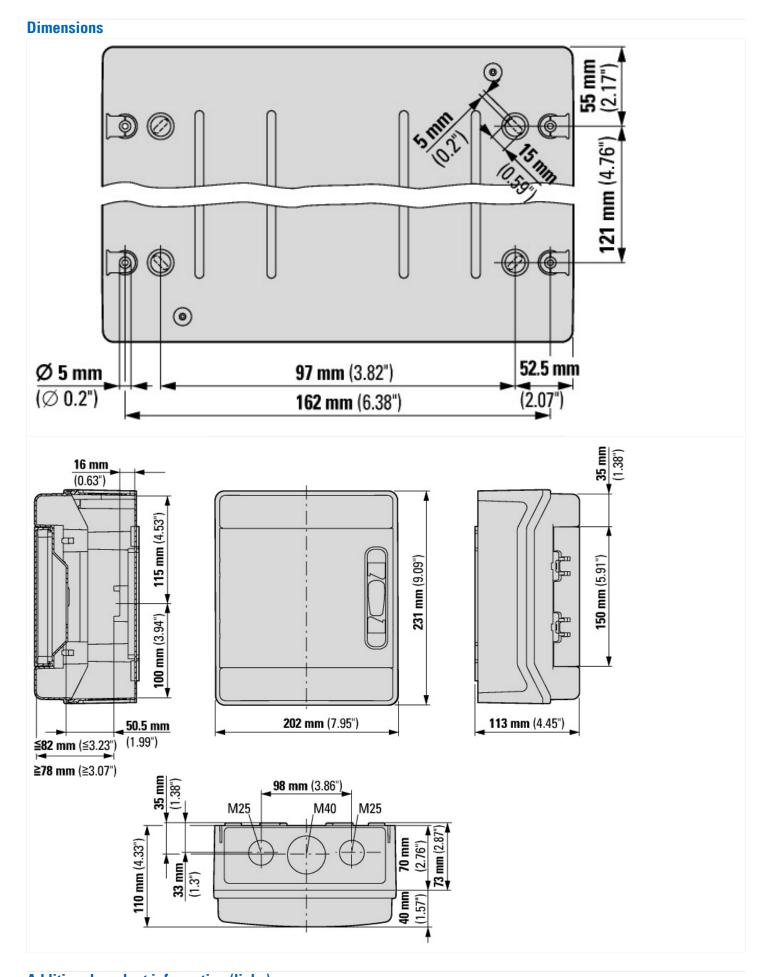
10.2 Strength of materials and parts 10.2.2 Corrosion resistance 10.2.3.1 Verification of thermal stability of enclosures 10.2.3.2 Verification of resistance of insulating materials to normal heat 10.2.3.3 Verification of resistance of insulating materials to normal heat 10.2.3.3 Verification of resistance of insulating materials to abnormal heat and fire due to internal electric effects 10.2.4 Resistance to ultra-violet (UV) radiation 10.2.5 Lifting 10.2.6 Mechanical impact 10.2.6 Mechanical impact 10.2.7 Inscriptions 10.3.0 Egree of protection of ASSEMBLIES 10.4 Clearances and creepage distances 10.5 Protection against electric shock 10.6 Incorporation of switching devices and components 10.7 Internal electrical circuits and connections 10.8 Incorporation of switching devices and components 10.9 Insulation properties 10.9 Insulation prop	IEC/EN 61439 design verification	
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10.2.3.2 Verification of resistance of insulating materials to normal heat and fire due to internal electric effects 10.2.3.3 Verification of resistance of insulating materials to abnormal heat and fire due to internal electric effects 10.2.4 Resistance to ultra-violet (UV) radiation	10.2.2 Corrosion resistance	Meets the product standard's requirements.
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	10.11 Short-circuit rating	Is the panel builder's responsibility.
10.13 Mechanical function Meets the product standard's requirements.	10.12 Electromagnetic compatibility	Is the panel builder's responsibility.
	10.13 Mechanical function	Meets the product standard's requirements.

Technical data ETIM 6.0

Distribution boards (EG000023) / Small distribution board (EC000214)

Electric engineering, automation, process control engineering / Electrical installation, device / Electrical distribution system (incl. small distribution board) / Small distribution board (ecl@ss8.1-27-14-24-09 [ACN387008])

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Mounting method		Surface mounting
Number of rows		1
Width in number of modular spacings		6
Type of cover		Door
Cover model		With notch
Transparent cover/door		Yes
Material housing		Plastic
Height	mm	231
Width	mm	202
Depth	mm	110
Built-in depth	mm	70
Internal depth	mm	60
DIN-rail		Yes
With mounting plate		No
Extension possible		Yes
EMC-version		No
Colour		Grey
RAL-number		7035
Degree of protection (IP)		IP65
With lock		No



Additional product information (links)

IL014003Z IKA compact distribution board	
IL014003Z IKA compact distribution board	ftp://ftp.moeller.net/D0CUMENTATION/AWA_INSTRUCTIONS/IL014003ZU2015_03.pdf
Product overview (Web)	http://www.eaton.eu/DE/Europe/Electrical/ProductsServices/Residential/index.htm